

700 MHz to 4200 MHz, Tx DGA

Data Sheet ADL5335

FEATURES

Differential input to single-ended output conversion Broad input frequency range: 700 MHz to 4200 MHz

Maximum gain: 12.0 dB typical Gain range of 20 dB typical Gain step size: 0.5 dB typical

Glitch free, thermometer-based digital step attenuator Fast attack, gain switching with programmable gain step Matched 50 Ω inputs and output

APPLICATIONS

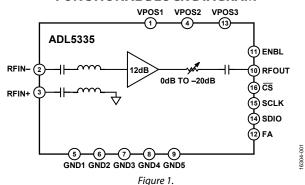
RF power control and calibration in wireless transmitters

GENERAL DESCRIPTION

The ADL5335 is a digital gain amplifier (DGA) optimized for use in wireless transmitters. A differential input and single-ended output facilitates a balun free connection between the broadband integrated transceivers with differential outputs and the RF gain blocks and drivers amplifiers with single-ended inputs.

The gain is programmable via a standard Analog Devices, Inc., serial peripheral interface (SPI) port from a maximum gain of 12.0 dB down to a minimum gain of -8.0 dB with a gain step

FUNCTIONAL BLOCK DIAGRAM



size of 0.5 dB. The ADL5335 also features a fast attack function where the gain can rapidly increase or decrease by the application of a single pulse.

The use of a thermometer-based digital step attenuator (DSA) ensures that gain changes are fundamentally glitch free. The ADL5335 is packaged in a 4 mm \times 4 mm, 16-lead LFCSP. A fully populated evaluation board and system demonstration platform (SDP)-based control software are available.

TABLE OF CONTENTS

Features	1
Applications	
Functional Block Diagram	
General Description	
Revision History	2
Specifications	3
Digital Logic Timing	6
Absolute Maximum Ratings	7
Thremal Resistance	7
FSD Caution	7

Pin Configuration and Function Descriptions	8
Typical Performance Characteristics	9
Theory of Operation	13
Basic Structure	13
Digital Interface Overview	13
Applications Information	15
Basic Connections	15
Outline Dimensions	16
Ordering Guide	16

REVISION HISTORY

12/2017—Revision 0: Initial Version

SPECIFICATIONS

VPOS1, VPOS2, VPOS3 = 5 V, T_A = 25°C, impedance out (Z_{OUT}) = 50 Ω , and a differential input drive, unless otherwise noted.

Table 1.

Parameter	Test Conditions/Comments	Min Typ Max	Unit	
OVERALL FUNCTION				
Input Frequency Range		700 4200) MHz	
Impedance				
Input	Differential input drive	50	Ω	
Output	Single-ended output	50	Ω	
GAIN CONTROL				
Gain Range		20	dB	
Maximum Gain		12.0	dB	
Minimum Gain		-8.0	dB	
Gain Step Size		0.5	dB	
BAND 8: 925 MHz TO 960 MHz				
Gain Range		20	dB	
Maximum Gain		13.0	dB	
Minimum Gain		-7.0	dB	
Gain Flatness	±200 MHz, all gains	0.3	dB	
Gain Step Error	All gain states	0.2	dB	
Group Delay Variation	Between any attenuation step	50	ps	
Output Third-Order Intercept (IP3)	Maximum gain, 4 dBm per tone	34	dBm	
	Minimum gain, –18 dBm per tone	13.6	dBm	
Output 1 dB Compression Point (P1dB)	Maximum gain	18.0	dBm	
	Minimum gain	-0.6	dBm	
Noise Figure	Maximum gain	5.4	dB	
-	Minimum gain	8.3	dB	
Return Loss				
Input		-18	dB	
Output	Minimum gain	-17	dB	
	Maximum gain	-30	dB	
Common-Mode Rejection Ratio (CMRR)	vs. frequency (±200 MHz)	20	dB	
BAND 3: 1805 MHz TO 1880 MHz				
Gain Range		20	dB	
Maximum Gain		12.8	dB	
Minimum Gain		-7.2	dB	
Gain Flatness	±200 MHz, all gains	0.5	dB	
Gain Step Error	All gain states	0.4	dB	
Group Delay Variation	Between any attenuation step	45	ps	
Output IP3	Maximum gain, 4 dBm per tone	33	dBm	
	Minimum gain, –18 dBm per tone	12	dBm	
Output P1dB	Maximum gain	18.3	dBm	
·	Minimum gain	0	dBm	
Noise Figure	Maximum gain	6.9	dB	
5	Minimum gain	10.6	dB	
Return Loss				
Input		-32	dB	
Output	Minimum gain	-23	dB	
·	Maximum gain	-17	dB	
CMRR	vs. frequency (±200 MHz)	22	dB	

Parameter	Test Conditions/Comments	Min Typ Max	Unit
BAND 1: 2110 MHz TO 2170 MHz			
Gain Range		20	dB
Maximum Gain		12.5	dB
Minimum Gain		-7.5	dB
Gain Flatness	±200 MHz, all gains	0.5	dB
Gain Step Error	All gain states	0.38	dB
Group Delay Variation	Between any attenuation step	20	ps
Output IP3	Maximum gain, 4 dBm per tone	32	dBm
	Minimum gain, –18 dBm per tone	11.6	dBm
Output P1dB	Maximum gain	18.1	dBm
	Minimum gain	-0.2	dBm
Noise Figure	Maximum gain	6.9	dB
Noise riguie	Minimum gain	10.4	dB
Return Loss	Willing gain	10.4	l ab
Input		-32	dB
-	Minimum gain	-32 -25	dB
Output	Minimum gain	-	
CLADD	Maximum gain	-19 25	dB
CMRR	vs. frequency (±200 MHz)	25	dB
BAND 7: 2620 MHz TO 2690 MHz			
Gain Range		20	dB
Maximum Gain		12.0	dB
Minimum Gain		-8.0	dB
Gain Flatness	±200 MHz, all gains	0.7	dB
Gain Step Error	All gain states	0.37	dB
Group Delay Variation	Between any attenuation step	30	ps
Output IP3	Maximum gain, 4 dBm per tone	32	dBm
	Minimum gain, –18 dBm per tone	13.1	dBm
Output P1dB	Maximum gain	17.8	dBm
	Minimum gain	-1.1	dBm
Noise Figure	Maximum gain	7.5	dB
J	Minimum gain	10.5	dB
Return Loss	, and the second		
Input		-19	dB
Output	Minimum gain	-24	dB
Catput	Maximum gain	_17	dB
CMRR	vs. frequency (±200 MHz)	26	dB
BAND 42: 3400 MHz TO 3600 MHz	vs. riequeriey (±200 Wi12)	25	ub.
Gain Range		20	dB
Maximum Gain		10.2	dB
Minimum Gain		-9.8	dВ
	1200 MH= -II		
Gain Flatness	±200 MHz, all gains	0.7	dB
Gain Step Error	All gain states	0.36	dB
Group Delay Variation	Between any attenuation step	20	ps
Output IP3	Maximum gain, 4 dBm per tone	31	dBm
	Minimum gain, –18 dBm per tone	10.9	dBm
Output P1dB	Maximum gain	16.8	dBm
	Minimum gain	2.3	dBm
Noise Figure	Maximum gain	7.5	dB
	Minimum gain	12.2	dB

Parameter	Test Conditions/Comments		Min Typ M		
Return Loss					
Input			-19		dB
Output	Minimum gain		-17		dB
	Maximum gain		-11		dB
CMRR	vs. frequency (±200 MHz)		28		dB
FREQUENCY = 4.2 GHz					
Gain Range			20		dB
Maximum Gain			9.3		dB
Minimum Gain			-10.7		dB
Gain Flatness	±200 MHz, all gains		0.9		dB
Gain Step Error	All gain states		0.49		dB
Group Delay Variation	Between any attenuation step		25		ps
Output IP3	Maximum gain, –4 dBm per tone		29		dBm
·	Minimum gain, –18 dBm per tone		11		dBm
Output P1dB	Maximum gain		15.8		dBm
·	Minimum gain		-3.7		dBm
Noise Figure	Maximum gain		8.7		dB
J	Minimum gain		13.5		dB
Return Loss	, and the second				
Input			-24		dB
Output	Minimum gain		-12		dB
•	Maximum gain		-11		dB
CMRR			29		dB
SPI PORT AND FAST ATTACK	SDIO, SCLK, CS, FA pins				
Logic Low				0.18	V
Logic High		1.62		1.8	V
Fast Attack Response Time			20		ns
ENABLE INTERFACE	ENBL pin				
Voltage Level					
To Enable	ENBL voltage (V _{ENBL}) increasing	1.62		1.8	V
To Disable	Enable/disable voltage (V _{ENBLDN}) increasing	0		0.18	V
Time					
Enable			30		ns
Disable			30		ns
POWER SUPPLY INTERFACE	VPOSx pins				
Supply Voltage	Main supply	4.75	5	5.25	V
Quiescent Current	Device enabled		125		mA
Power Consumption	Device enabled		625		mW
·	Power-down mode		18.5		mW

DIGITAL LOGIC TIMING

Table 2.

Parameter	Description	Min	Тур	Max	Unit
t _{CLK}	Maximum serial clock rate		25		MHz
t _{HI}	Minimum period that SCLK is in a logic high state		10		ns
t _{LO}	Minimum period that SCLK is in a logic low state		10		ns
t_{S}	Setup time between falling edge of $\overline{\text{CS}}$ and SCLK		15		ns
tн	Hold time between data and rising edge of SCLK		5		ns
t_{DS}	Setup time between data and rising edge of SCLK		15		ns
t_{DH}	SCLK to SDIO Hold Time		10		ns
t_{Z}	Maximum time delay between CS deactivation and SDIO bus to return to high impedance		5		ns
taccess	Maximum time delay between falling edge of SCLK and out data valid for a read operation		5		ns

SPI Timing Diagram

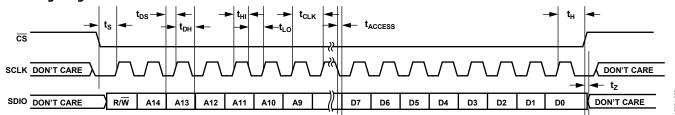


Figure 2. SPI Timing

ABSOLUTE MAXIMUM RATINGS

Table 3.

Parameter	Rating
Supply Voltage, V _{POS}	5.5 V
SCLK, SDIO, CS, FA	3.9 V
Enable Voltage, ENBL	2.2 V
Input Average RF Power	12 dBm
Equivalent Voltage, Sine Wave Input ¹	2.5 V p-p
Internal Power Dissipation	725 mW
Maximum Junction Temperature	150°C
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	−65°C to +150°C
Lead Temperature (Soldering, 60 sec)	300°C

 $^{^1}$ If the common-mode voltage at the inputs (V_{COM}) is closer than 0.625 V from either rail voltage (V_{RAIL}), the equivalent voltage reduces to (|V_{RAIL} – V_{COM}|) \times 4, where V_{RAIL} is the rail closest to V_{COM}.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THREMAL RESISTANCE

Thermal performance is directly linked to printed circuit board (PCB) design and operating environment. Careful attention to PCB thermal design is required.

Table 4 shows the thermal resistance from the die to ambient (θ_{JA}) and die to lead (θ_{JC}) , respectively.

Table 4. Thermal Resistance

Package Type	θ _{JA}	θις	Unit
CP-16-39	58.7	2.2	°C/W

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

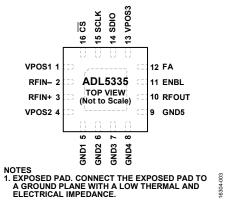


Figure 3. Pin Configuration

Table 5. Pin Function Descriptions

Pin No.	Mnemonic	Description
1, 4, 13	VPOS1, VPOS2, VPOS3	Power Supplies. Separately decouple each power supply pin using 100 pF and 0.1µF capacitors.
2, 3	RFIN-, RFIN+	RF Negative and Positive Inputs. These pins have a 50 Ω differential input pair and are internally accoupled.
5 to 9	GND1, GND2, GND3, GND4, GND5	Ground. Connect these ground pins to a low impedance ground plane.
10	RFOUT	RF Output. This pin has a 50 Ω single-ended output and is internally ac-coupled.
11	ENBL	Enable. A logic high on this pin (1.8 V logic) enables operation and a logic low on this pin puts the device in a low power sleep mode.
12	FA	Fast Attack. A logic high on this pin (1.8 V logic) decreases the programmed gain by an additional 2 dB, 4 dB, 8 dB, or 16 dB. The fast attack attenuation step is defined by the last two bits of an 8-bit programming byte that is written to the device via the SPI. When FA returns to a logic low, the gain returns to its normal programmed level. When not using the fast attack function, tie the FA pin to ground.
14	SDIO	Serial Data Input/Output (SDIO), 1.8 V Logic. The gain and fast attack attenuation levels are programmed using eight bits (Register Address 0x100). The 24-bit write consists of an R/W bit, a 15-bit register address, and the eight bits of data. The first six bits of data set the gain and the last two bits set the fast attack attenuation (–2 dB, –4 dB, –8 dB, or –16 dB).
15	SCLK	Serial Clock (SCLK), 1.8 V Logic. The gain and fast attack attenuation levels are programmed using eight bits (Register Address 0x100). The 24-bit write consists of an R/W bit, a 15-bit register address, and the eight bits of data. The first six bits of data set the gain and the last two bits set the fast attack attenuation (–2 dB, –4 dB, –8 dB, or –16 dB).
16	CS	Chip Select Bar (CS), 1.8 V Logic. The gain and fast attack attenuation levels are programmed using eight bits (Register Address 0x100). The 24-bit write consists of an R/W bit, a 15-bit register address, and the eight bits of data. The first six bits of data set the gain and the last two bits set the fast attack attenuation (–2 dB, –4 dB, –8 dB, or –16 dB).
	EP	Exposed Pad. Connect the exposed pad to a ground plane with a low thermal and electrical impedance.

TYPICAL PERFORMANCE CHARACTERISTICS

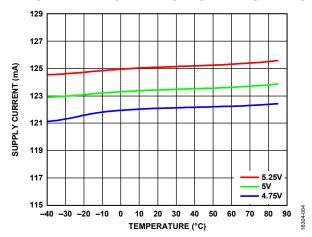


Figure 4. Supply Current vs. Temperature for Various Power Supplies (V_{POS})

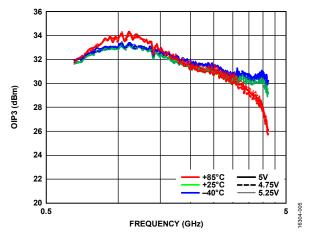


Figure 5. Output Third-Order Intercept (OIP3) vs. Frequency for Various V_{POS} and Temperatures, Maximum Gain = 12 dB, Output Tones = 4 dBm

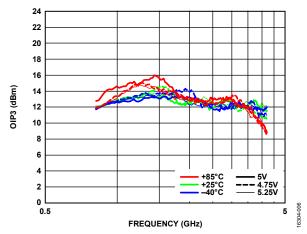


Figure 6. OIP3 vs. Frequency for Various V_{POS} and Temperatures, Minimum Gain = -8 dB, Output Tones = -18 dBm

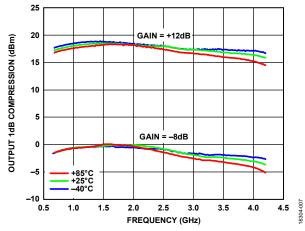


Figure 7. Output 1dB Compression vs. Frequency for Various Temperatures and Gains, $V_{POS} = 5 V$

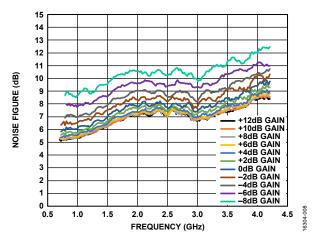


Figure 8. Noise Figure vs. Frequency for Various Gain Steps at $V_{POS} = 5 V$

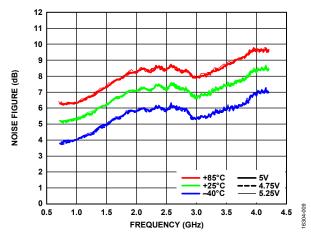


Figure 9. Noise Figure vs. Frequency for Various Temperatures and V_{POS} at Maximum Gain = 12 dB

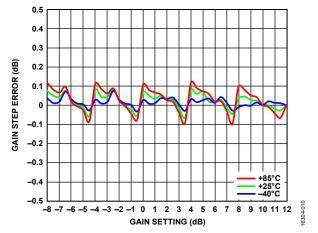


Figure 10. Gain Step Error vs. Gain Setting for Various Temperatures, $V_{POS} = 5 V$

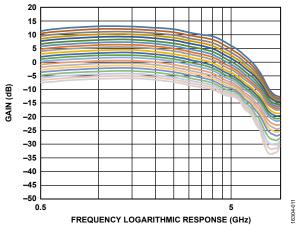


Figure 11. Gain vs. Frequency Logarithmic Response with a Maximum Gain = +12 dB to a Minimum Gain = -8 dB in 1 dB Steps

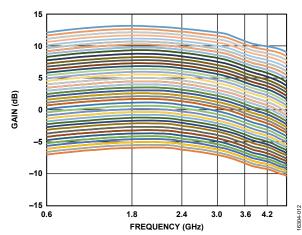


Figure 12. Gain vs. Frequency for All Gain Steps (+12 dB to -8 dB, 0.5 dB Step Size), $V_{POS} = 5$ V, Temperature = 25°C

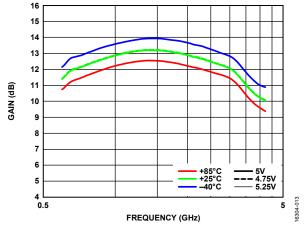


Figure 13. Gain vs. Frequency for Various Temperatures and V_{POS}

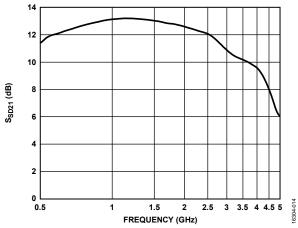


Figure 14. Forward Transmission (S_{SD21}) vs. Frequency, Gain = 12 dB

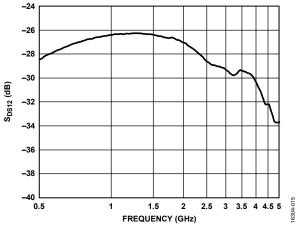


Figure 15. Reverse Transmission (S_{DS12}) vs. Frequency, Gain = 12 dB

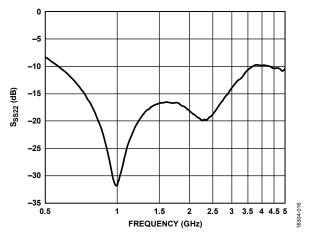


Figure 16. Output Reflection Coefficient (S_{SS22}) vs. Frequency, Gain = 12 dB

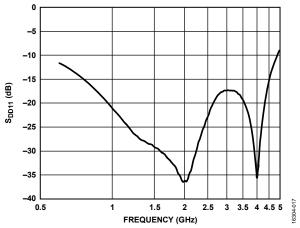


Figure 17. Input Reflection Coefficient (S_{DD11}) vs. Frequency, Gain = 12 dB

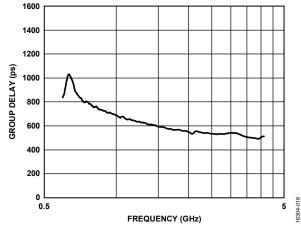


Figure 18. Group Delay vs. Frequency, Gain = 12 dB

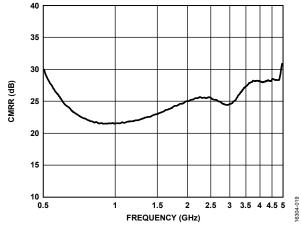


Figure 19. Common-Mode Rejection Ratio (CMRR) vs. Frequency, Gain = 12 dB

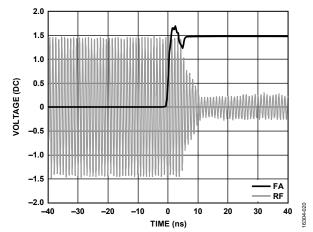


Figure 20. Fast Attack Response, On at 16 dB

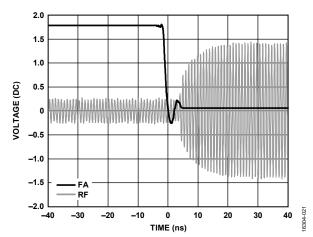


Figure 21. Fast Attack Response, Off at 16 dB

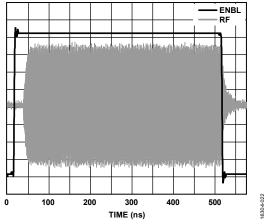


Figure 22. Enable/Disable Time Domain Response

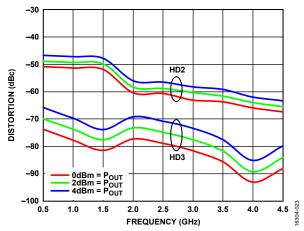


Figure 23. Distortion (HD2 and HD3) vs. Frequency for Various Output Powers (P_{OUT})

THEORY OF OPERATION

BASIC STRUCTURE

The ADL5335 is an SPI controlled DGA. An integrated, on-chip balun converts a 50 Ω differential RF input into a 50 Ω single-ended RF output. The RF inputs and the RF output utilize internal ac coupling capacitors.

The DGA core consists of a fixed gain amplifier and digitally controlled attenuator. The amplifier has a gain of 12.0 dB. The attenuator has a range of 0 dB to -8.0 dB with +0.5 dB steps and uses a thermometer coding technique to eliminate transient glitches during gain changes.

DIGITAL INTERFACE OVERVIEW

The ADL5335 digital section includes an enable pin (ENBL), a fast attack pin (FA), and a SPI.

Serial Peripheral Interface (SPI)

The SPI uses the three following pins: the serial data input/output (SDIO), the serial clock (SCLK), and the chip select bar (\overline{CS}) .

The SPI data register consists of three bytes: one read/write bit (R/W), 15 address bits (A14 to A0), two fast attack (FA) attenuation step size bits (D7 and D6), and six gain control bits (D5 to D0), as shown in Figure 24.

The gain code and fast attack attenuation step size bits are controlled via Register Address 0x100. See Table 6 and Table 7, respectively, for their truth tables.

Table 6. Gain Code Truth Table

6-Bit Binary Gain Code, Bits[D5:D0]	Gain (dB)
000000	+12.0
000001	+11.5
000010	+11.0
000011	+10.5
000100	+10.0
000101	+9.5
000110	+9.0
000111	+8.5
001000	+8.0
001001	+7.5
001010	+7.0
001011	+6.5
001100	+6.0
001101	+5.5
001110	+5.0
001111	+4.5

6-Bit Binary Gain Code, Bits[D5:D0]	Gain (dB)
010000	+4.0
010001	+3.5
010010	+3.0
010011	+2.5
010100	+2.0
010101	+1.5
010110	+1.0
010111	+0.5
011000	0
011001	-0.5
011010	-1.0
011011	-1.5
011100	-2.0
011101	-2.5
011110	-3.0
011111	-3.5
100000	-4.0
100001	-4.5
100010	-5.0
100011	-5.5
100100	-6.0
100101	-6.5
100110	-7.0
100111	-7.5
101000	-8.0
100011 to 111111	-8.0

Fast Attack (FA)

The fast attack feature allows the gain to be reduced from its present setting by a predetermined step size. Four different attenuation step sizes are available (see Table 7).

The FA pin controls fast attack mode. A logic high on the FA pin results in an attenuation that is selected by Bits[D7:D6] in the SPI register (Register Address 0x100).

Table 7. Fast Attack Attenuation Step Size Truth Table

6-Bit Binary Gain Code, Bits[D7:D6]	Step Size (dB)
00	-2
01	-4
10	-8
11	-16

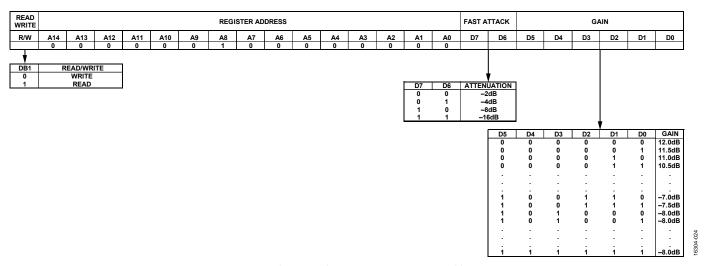


Figure 24. Gain and Fast Attack Programming via Register Address 0x100

APPLICATIONS INFORMATION BASIC CONNECTIONS

Figure 25 shows the basic connections for operating the ADL5335. Apply a 5 V voltage to the supply pins (VPOS1, VPOS2, and VPOS3). Decouple each supply pin with at least one low inductance, surface-mount ceramic, 0.1 μF capacitor placed as close to the device as possible. The balanced differential inputs are decoupled using 100 pF capacitors and so is the 50 Ω load on the RF output. The serial peripheral interface pins (SCLK,

SDIO, and $\overline{\text{CS}}$), fast attack (FA), and enable (ENBL) pins operate at an 1.8 V voltage. To enable the ADL5335, pull the ENBL pin high (1.8 V). A low on the ENBL pin sets the device to power-down mode, reducing the current to approximately 3.7 mA.

For additional information on device operation, see the EV-ADL5335SD1Z User Guide.

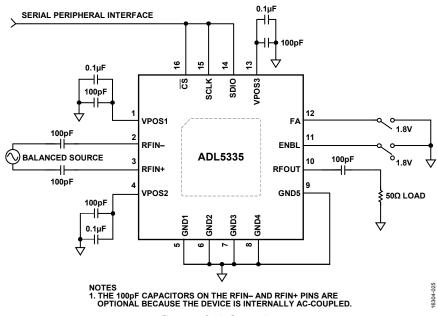


Figure 25. Basic Connections

OUTLINE DIMENSIONS

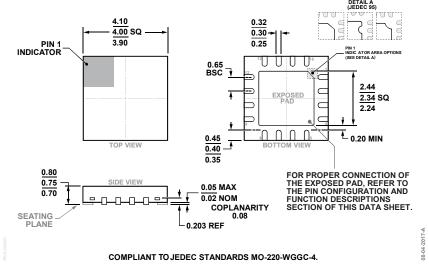


Figure 26. 16-Lead Lead Frame Chip Scale Package [LFCSP] 4 mm × 4 mm Body and 0.75 mm Package Height (CP-16-39) Dimensions shown in millimeters

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Package Option
ADL5335ACPZN	-40°C to +85°C	16-Lead Lead Frame Chip Scale Package [LFCSP]	CP-16-39
ADL5335ACPZN-R7	-40°C to +85°C	16-Lead Lead Frame Chip Scale Package [LFCSP]	CP-16-39
EV-ADL5335SD1Z		Evaluation Board	

¹ Z = RoHS Compliant Part.



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AD534LDZ AD534SD AD534TD AD539JDZ AD539JNZ AD539KDZ AD539KNZ AD600JNZ AD604ARSZ AD605ANZ AD605ARZ

AD605BRZ AD633ANZ AD633JNZ AD600JRZ-R7 AD8018ARUZ AD8260ACPZ-WP AD8324ACPZ AD8330ACPZ-R7 AD8334ACPZ AD8337BCPZ-REEL7 AD8337BCPZ-WP AD8367ARUZ-RL7 AD8369ARUZ-REEL7 AD8392AAREZ

AD8375ACPZ-R7 AD8260ACPZ-R7 AD8369ARUZ AD8398ACPZ-R2 AD8331ARQZ